

# 74VHC123A

## Dual Retriggerable Monostable Multivibrator

### Features

- High Speed:  $t_{PD} = 8.1ns$  (Typ.) at  $T_A = 25^\circ C$
- Low Power Dissipation:  $I_{CC} = 4\mu A$  (Max) at  $T_A = 25^\circ C$
- Active State:  $I_{CC} = 600\mu A$  (Max.) at  $T_A = 25^\circ C$
- High Noise Immunity:  $V_{NIH} = V_{NIL} = 28\% V_{CC}$  (Min.)
- Power down protection is provided on all inputs
- Pin and function compatible with 74HC123A

### General Description

The VHC123A is an advanced high speed CMOS Monostable Multivibrator fabricated with silicon gate CMOS technology. It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. Each multivibrator features both a negative, A, and a positive, B, transition triggered input, either of which can be used as an inhibit input. Also included is a clear input that when taken low resets the one-shot. The VHC123A can be triggered on the positive transition of the clear while A is held low and B is held high. The output pulse width is determined by the equation:  $PW = (R_x)(C_x)$ ; where PW is in seconds, R is in ohms, and C is in farads.

#### Limits for $R_x$ and $C_x$ are:

External capacitor,  $C_x$ : No limit

External resistors,  $R_x$ :  $V_{CC} = 2.0V, 5 k\Omega$  min  
 $V_{CC} > 3.0V, 1 k\Omega$  min

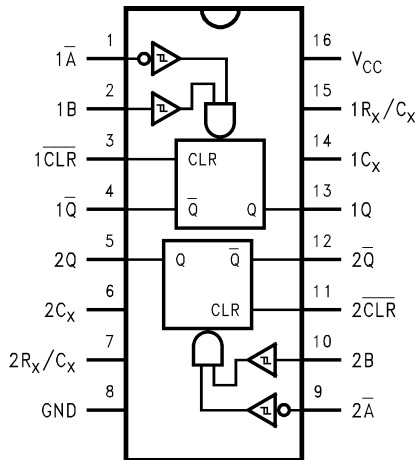
An input protection circuit ensures that 0 to 7V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5V to 3V systems and two supply systems such as battery back up. This circuit prevents device destruction due to mismatched supply and input voltages.

### Ordering Information

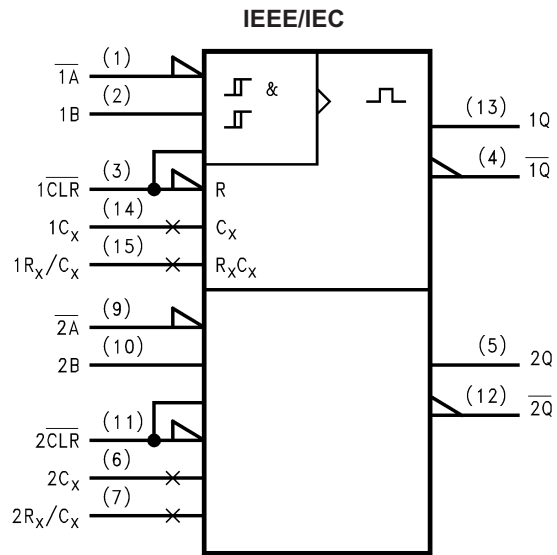
Order Number	Package Number	Package Description
74VHC123AM	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74VHC123ASJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHC123AMTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter "X" to the ordering number.

### Connection Diagram



### Logic Symbol



### Pin Description

Pin Names	Description
A	Trigger Inputs (Negative Edge)
B	Trigger Inputs (Positive Edge)
CLR	Reset Inputs
C <sub>x</sub>	External Capacitor
R <sub>x</sub>	External Resistor
Q, Q̄	Outputs

### Truth Table

Inputs			Outputs		Function
Ā	B	CLR	Q	Q̄	
↘	H	H	⌋	⌌	Output Enable
X	L	H	L	H	Inhibit
H	X	H	L	H	Inhibit
L	↗	H	⌋	⌌	Output Enable
L	H	↗	⌋	⌌	Output Enable
X	X	L	L	H	Reset

H = HIGH Voltage Level

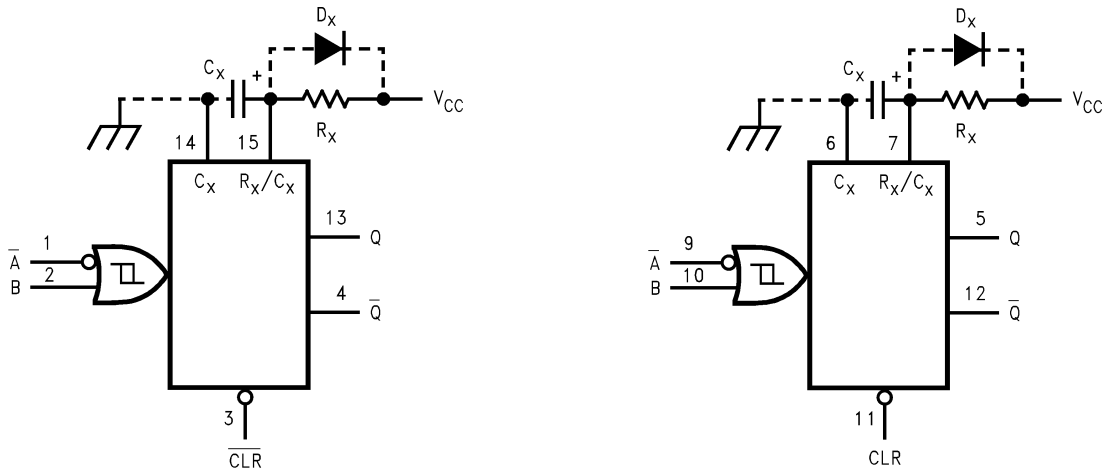
L = LOW Voltage Level

↘ = HIGH-to-LOW Transition

↗ = LOW-to-HIGH Transition

X = Don't Care

## Block Diagrams



**Note A:**  $C_x$ ,  $R_x$ ,  $D_x$  are external Capacitor, Resistor, and Diode, respectively.

**Note B:** External clamping diode,  $D_x$ ;

External capacitor is charged to  $V_{CC}$  level in the wait state, i.e. when no trigger is applied.

If the supply voltage is turned off,  $C_x$  discharges mainly through the internal (parasitic) diode. If  $C_x$  is sufficiently large and  $V_{CC}$  drops rapidly, there will be some possibility of damaging the IC through inrush current or latch-up. If the capacitance of the supply voltage filter is large enough and  $V_{CC}$  drops slowly, the inrush current is automatically limited and damage to the IC is avoided.

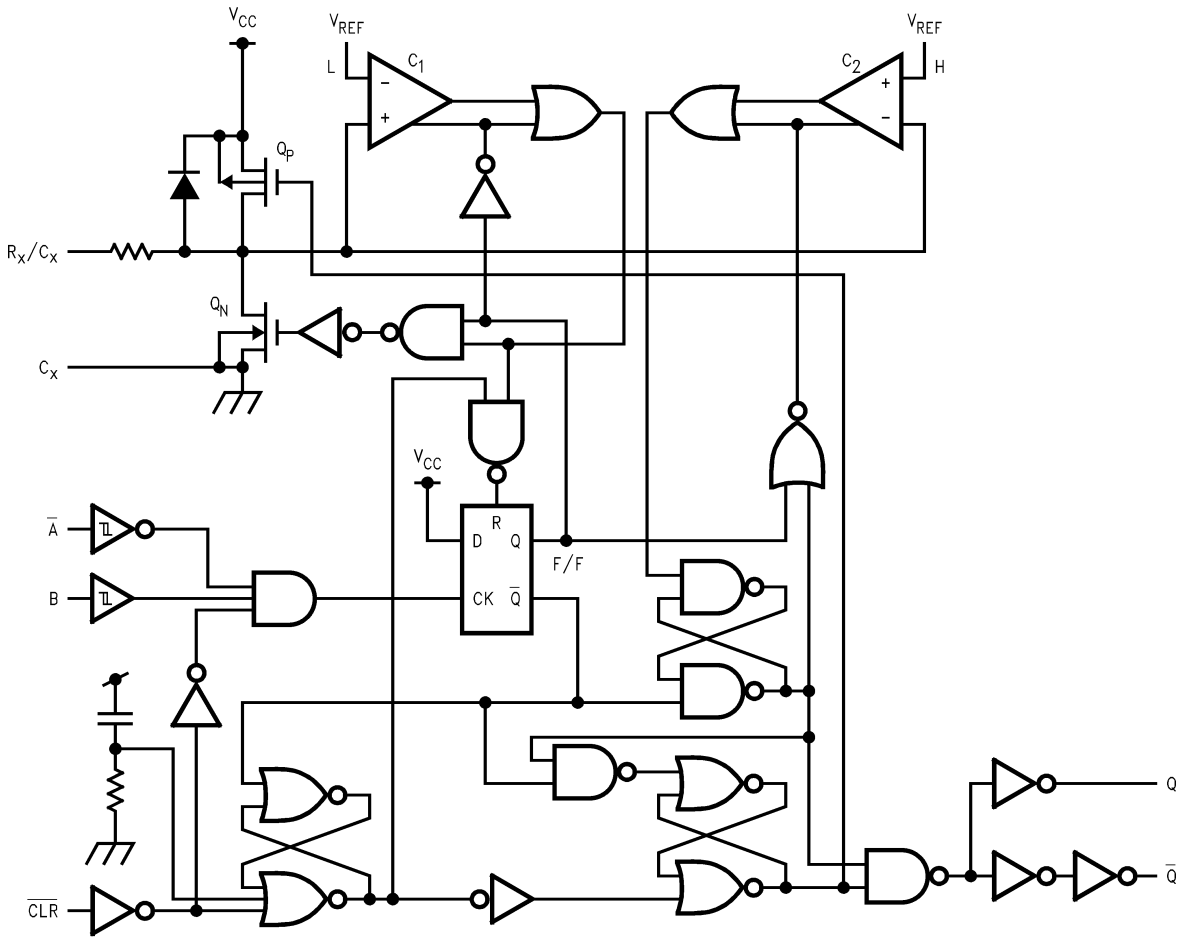
The maximum value of forward current through the parasitic diode is  $\pm 20\text{mA}$ . In the case of a large  $C_x$ , the limit of fall time of the supply voltage is determined as follows:

$$t_f \geq (V_{CC} - 0.7) C_x / 20\text{mA}$$

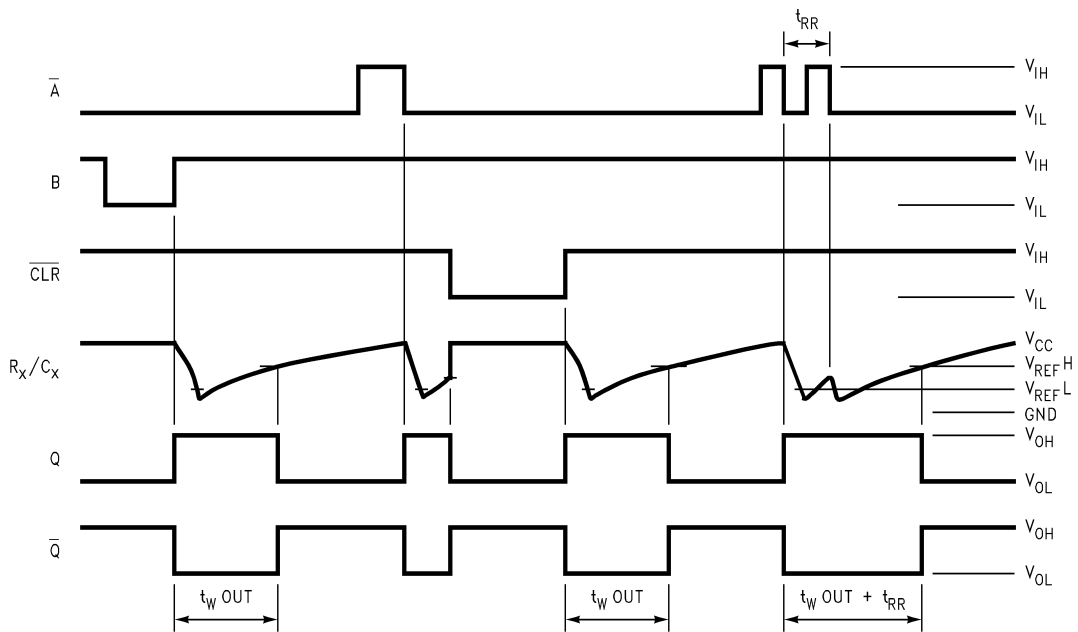
( $t_f$  is the time between the supply voltage turn off and the supply voltage reaching  $0.4 V_{CC}$ )

In the event a system does not satisfy the above condition, an external clamping diode ( $D_x$ ) is needed to protect the IC from inrush current.

System Diagram



Timing Chart



## Functional Description

### 1. Stand-by State

The external capacitor ( $C_x$ ) is fully charged to  $V_{CC}$  in the Stand-by State. That means, before triggering, the  $Q_P$  and  $Q_N$  transistors which are connected to the  $R_x/C_x$  node are in the off state. Two comparators that relate to the timing of the output pulse, and two reference voltage supplies turn off. The total supply current is only leakage current.

### 2. Trigger Operation

Trigger operation is effective in any of the following three cases. First, the condition where the  $\bar{A}$  input is LOW, and B input has a rising signal; second, where the B input is HIGH, and the A input has a falling signal; and third, where the  $\bar{A}$  input is LOW and the B input is HIGH, and the  $\overline{CLR}$  input has a rising signal.

After a trigger becomes effective, comparators  $C_1$  and  $C_2$  start operating, and  $Q_N$  is turned on. The external capacitor discharges through  $Q_N$ . The voltage level at the  $R_x/C_x$  node drops. If the  $R_x/C_x$  voltage level falls to the internal reference voltage  $V_{refL}$ , the output of  $C_1$  becomes LOW. The flip-flop is then reset and  $Q_N$  turns off. At that moment  $C_1$  stops but  $C_2$  continues operating.

After  $Q_N$  turns off, the voltage at the  $R_x/C_x$  node starts rising at a rate determined by the time constant of external capacitor  $C_x$  and resistor  $R_x$ .

Upon triggering, output Q becomes HIGH, following some delay time of the internal F/F and gates. It stays HIGH even if the voltage of  $R_x/C_x$  changes from falling to rising. When  $R_x/C_x$  reaches the internal reference voltage  $V_{refH}$ , the output of  $C_2$  becomes LOW,

the output Q goes LOW and  $C_2$  stops its operation. That means, after triggering, when the voltage level of the  $R_x/C_x$  node reaches  $V_{refH}$ , the IC returns to its MONOSTABLE state.

With large values of  $C_x$  and  $R_x$ , and ignoring the discharge time of the capacitor and internal delays of the IC, the width of the output pulse,  $t_W$  (OUT), is as follows:

$$t_W (\text{OUT}) = 1.0 C_x R_x$$

### 3. Retrigger operation (74VHC123A)

When a new trigger is applied to either input  $\bar{A}$  or B while in the MONOSTABLE state, it is effective only if the IC is charging  $C_x$ . The voltage level of the  $R_x/C_x$  node then falls to  $V_{refL}$  level again. Therefore the Q output stays HIGH if the next trigger comes in before the time period set by  $C_x$  and  $R_x$ .

If the new trigger is very close to a previous trigger, such as an occurrence during the discharge cycle, it will have no effect.

The minimum time for a trigger to be effective 2nd trigger,  $t_{RR}$  (Min), depends on  $V_{CC}$  and  $C_x$ .

### 4. Reset Operation

In normal operation, the  $\overline{CLR}$  input is held HIGH. If  $\overline{CLR}$  is LOW, a trigger has no affect because the Q output is held LOW and the trigger control F/F is reset. Also,  $Q_P$  turns on and  $C_x$  is charged rapidly to  $V_{CC}$ .

This means if  $\overline{CLR}$  is set LOW, the IC goes into a wait state.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
$V_{CC}$	Supply Voltage	-0.5V to +7.0V
$V_{IN}$	DC Input Voltage	-0.5V to +7.0V
$V_{OUT}$	DC Output Voltage	-0.5V to $V_{CC} + 0.5V$
$I_{IK}$	Input Diode Current	-20mA
$I_{OK}$	Output Diode Current	$\pm 20mA$
$I_{OUT}$	DC Output Current	$\pm 25mA$
$I_{CC}$	DC $V_{CC}$ / GND Current	$\pm 50mA$
$T_{STG}$	Storage Temperature	-65°C to +150°C
$T_L$	Lead Temperature (Soldering, 10 seconds)	260°C

## Recommended Operating Conditions<sup>(1)</sup>

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
$V_{CC}$	Supply Voltage	2.0V to +5.5V
$V_{IN}$	Input Voltage	0V to +5.5V
$V_{OUT}$	Output Voltage	0V to $V_{CC}$
$T_{OPR}$	Operating Temperature	-40°C to +85°C
$t_r, t_f$	Input Rise and Fall Time ( $\overline{CLR}$ only) $V_{CC} = 3.3V \pm 0.3V$ $V_{CC} = 5.0V \pm 0.5V$	0ns/V ~ 100ns/V 0ns/V ~ 20ns/V
	External Capacitor, $C_x$	No Limitation <sup>(2)</sup> F
	External Resistor, $R_x$	>5k $\Omega$ <sup>(2)</sup> ( $V_{CC} = 2.0V$ ) >1k $\Omega$ <sup>(2)</sup> ( $V_{CC} > 3.0V$ )

### Notes:

- Unused inputs must be held HIGH or LOW. They may not float.
- The maximum allowable values of  $C_x$  and  $R_x$  are a function of the leakage of capacitor  $C_x$ , the leakage of the device, and leakage due to board layout and surface resistance. Susceptibility to externally induced noise signals may occur for  $R_x > 1M\Omega$ .

## DC Electrical Characteristics

Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40° to 85°C		Units
				Min.	Typ.	Max.	Min.	Max.	
V <sub>IH</sub>	HIGH Level Input Voltage	2.0		1.50			1.50		V
		3.0–5.5		0.7 x V <sub>CC</sub>			0.7 x V <sub>CC</sub>		
V <sub>IL</sub>	LOW Level Input Voltage	2.0				0.50	0.50	V	
		3.0–5.5				0.3 x V <sub>CC</sub>	0.3 x V <sub>CC</sub>		
V <sub>OH</sub>	HIGH Level Output Voltage	2.0	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -50μA	1.9	2.0		1.9	V
		3.0			2.9	3.0		2.9	
		4.5			4.4	4.5		4.4	
		3.0		I <sub>OH</sub> = -4mA	2.58			2.48	
		4.5			I <sub>OH</sub> = -8mA	3.94			
V <sub>OL</sub>	LOW Level Output Voltage	2.0	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 50μA		0.0	0.1	0.1	V
		3.0				0.0	0.1	0.1	
		4.5				0.0	0.1	0.1	
		3.0		I <sub>OL</sub> = 4mA			0.36	0.44	
		4.5			I <sub>OL</sub> = 8mA			0.36	
I <sub>IN</sub>	Input Leakage Current	0–5.5	V <sub>IN</sub> = 5.5V or GND			±0.1		±1.0	μA
I <sub>IN</sub>	R <sub>x</sub> /C <sub>x</sub> Terminal Off-State Current	5.5	V <sub>IN</sub> = V <sub>CC</sub> or GND			±0.25		±2.50	μA
I <sub>CC</sub>	Quiescent Supply Current	5.5	V <sub>IN</sub> = V <sub>CC</sub> or GND			4.0		40.0	μA
I <sub>CC</sub>	Active—State <sup>(3)</sup> Supply Current	3.0	V <sub>IN</sub> = V <sub>CC</sub> or GND, R <sub>x</sub> /C <sub>x</sub> = 0.5 V <sub>CC</sub>		160	250		280	μA
		4.5			380	500		650	
		5.5			560	750		975	

**Note:**

3. Per circuit.

AC Electrical Characteristics<sup>(4)</sup>

Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to +85°C		Units
				Min.	Typ.	Max.	Min.	Max.	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay Time (A, B-Q, Q̄)	3.3 ± 0.3	C <sub>L</sub> = 15 pF		13.4	20.6	1.0	24.0	ns
			C <sub>L</sub> = 50 pF		15.9	24.1	1.0	27.5	
		5.0 ± 0.5	C <sub>L</sub> = 15 pF		8.1	12.0	1.0	14.0	ns
			C <sub>L</sub> = 50 pF		9.6	14.0	1.0	16.0	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay Time (CLR Trigger—Q, Q̄)	3.3 ± 0.3	C <sub>L</sub> = 15 pF		14.5	22.4	1.0	26.0	ns
			C <sub>L</sub> = 50 pF		17.0	25.9	1.0	29.5	
		5.0 ± 0.5	C <sub>L</sub> = 15 pF		8.7	12.9	1.0	15.0	ns
			C <sub>L</sub> = 50 pF		10.2	14.9	1.0	17.0	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay Time (CLR—Q, Q̄)	3.3 ± 0.3	C <sub>L</sub> = 15 pF		10.3	15.8	1.0	18.5	ns
			C <sub>L</sub> = 50 pF		12.8	19.3	1.0	22.0	
		5.0 ± 0.5	C <sub>L</sub> = 15 pF		6.3	9.4	1.0	11.0	ns
			C <sub>L</sub> = 50 pF		7.8	11.4	1.0	13.0	
t <sub>WOUT</sub>	Output Pulse Width	3.3 ± 0.3	C <sub>L</sub> = 50pF, C <sub>x</sub> = 28pF,		160	240		300	ns
			5.0 ± 0.5	R <sub>x</sub> = 2kΩ		133	200		
		3.3 ± 0.3	C <sub>L</sub> = 50pF, C <sub>x</sub> = 0.01μF,	90	100	110	90	110	μs
			5.0 ± 0.5	R <sub>x</sub> = 10kΩ	90	100	110	90	
		3.3 ± 0.3	C <sub>L</sub> = 50pF, C <sub>x</sub> = 0.1μF,	0.9	1.0	1.1	0.9	1.1	ms
			5.0 ± 0.5	R <sub>x</sub> = 1kΩ	0.9	1.0	1.1	0.9	
Δt <sub>WOUT</sub>	Output Pulse Width Error Between Circuits (In same Package)				±1				%
C <sub>IN</sub>	Input Capacitance		V <sub>CC</sub> = Open		4	10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance		<sup>(5)</sup>		73				pF

**Notes:**

4. Refer to Timing Chart.

5. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:

$$I_{CC}(\text{opr.}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}^1 \cdot \text{Duty} / 100 + I_{CC} / 2 \text{ (per Circuit)}$$

I<sub>CC</sub><sup>1</sup>: Active Supply Current

Duty: %



### AC Operating Requirement<sup>(6)</sup>

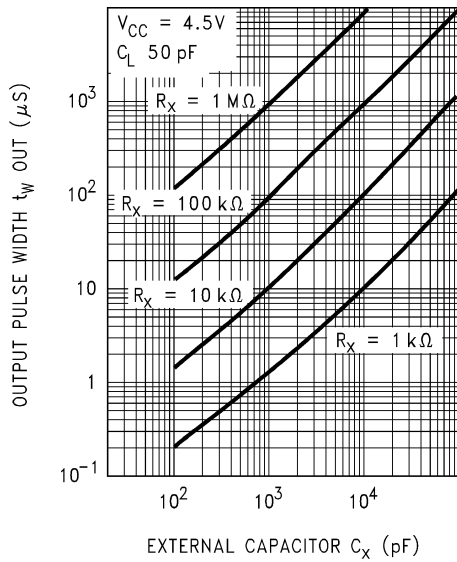
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C to +85°C		Units
				Min.	Typ.	Max.	Min.	Max.	
t <sub>W(L)</sub> , t <sub>W(H)</sub>	Minimum Trigger Pulse Width	3.3		5.0			5.0		ns
		5.0		5.0			5.0		
t <sub>W(L)</sub>	Minimum Clear Pulse Width	3.3		5.0			5.0		ns
		5.0		5.0			5.0		
t <sub>RR</sub>	Minimum Retrigger Time	3.3 ± 0.3	R <sub>x</sub> = 1kΩ, C <sub>x</sub> = 100pF		60				ns
		5.0 ± 0.5			39				
		3.3	R <sub>x</sub> = 1kΩ, C <sub>x</sub> = 0.01μF		1.5				μs
		5.0			1.2				

**Note:**

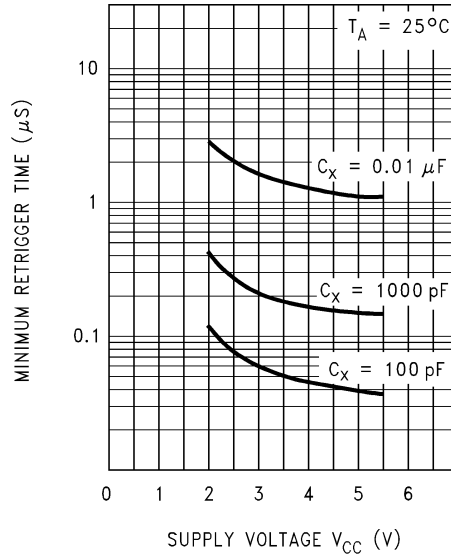
6. Refer to Timing Chart.

### Device Characteristics

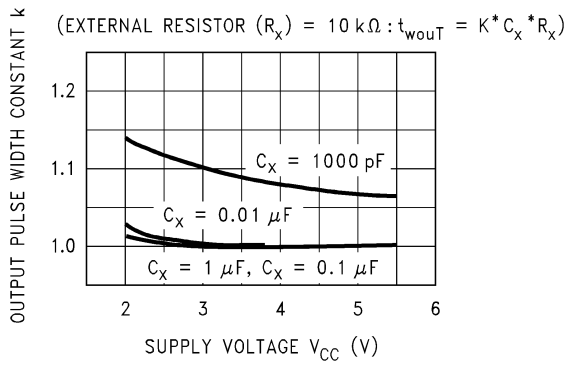
$t_{wout} * C_x$  Characteristics (Typ.)



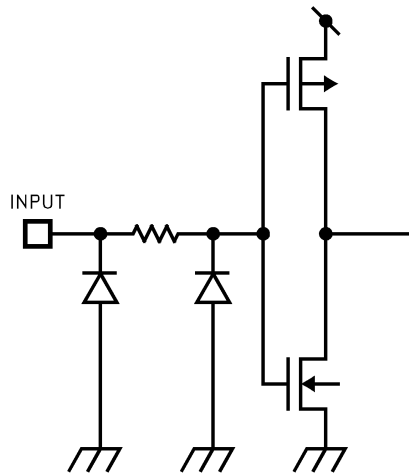
$t_{RR} * V_{CC}$  Characteristics (Typ.)



Output Pulse Width Constant K-Supply Voltage (Typ.)

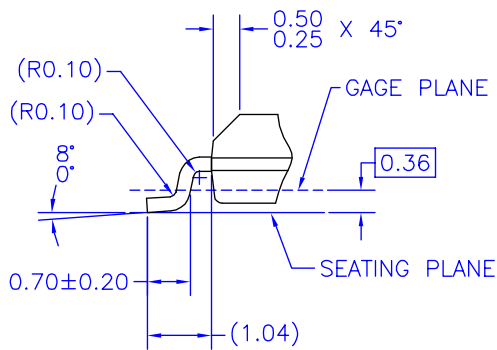
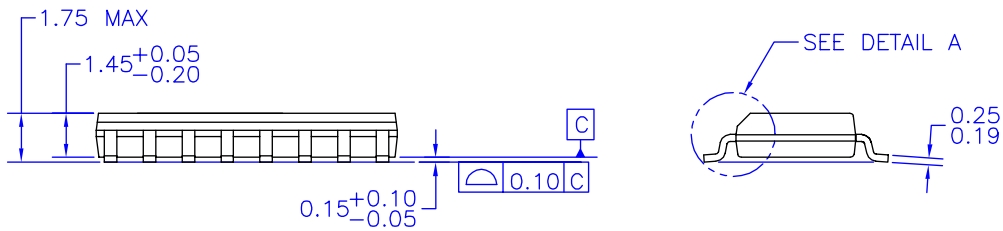
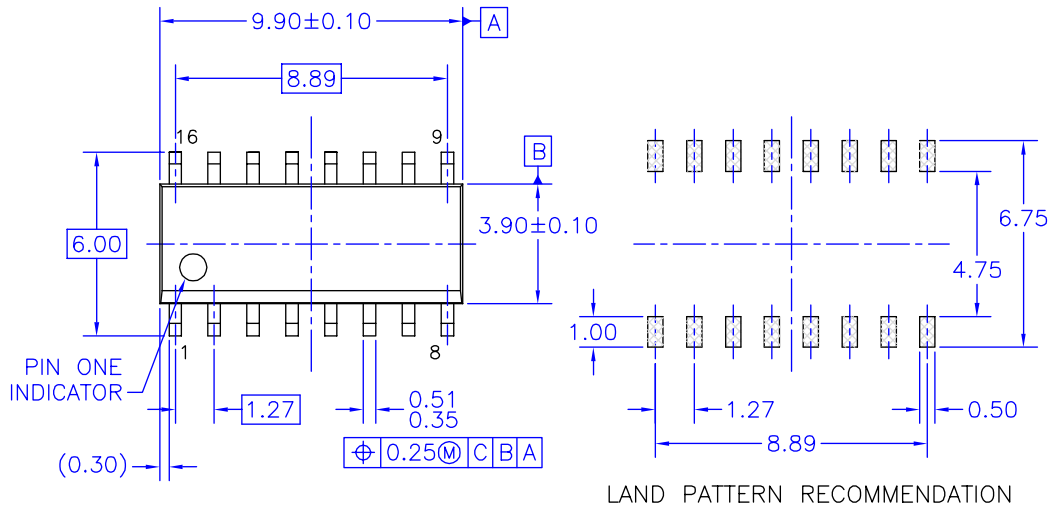


Input Equivalent Circuit



### Physical Dimensions

Dimensions are in millimeters unless otherwise noted.



NOTES: UNLESS OTHERWISE SPECIFIED

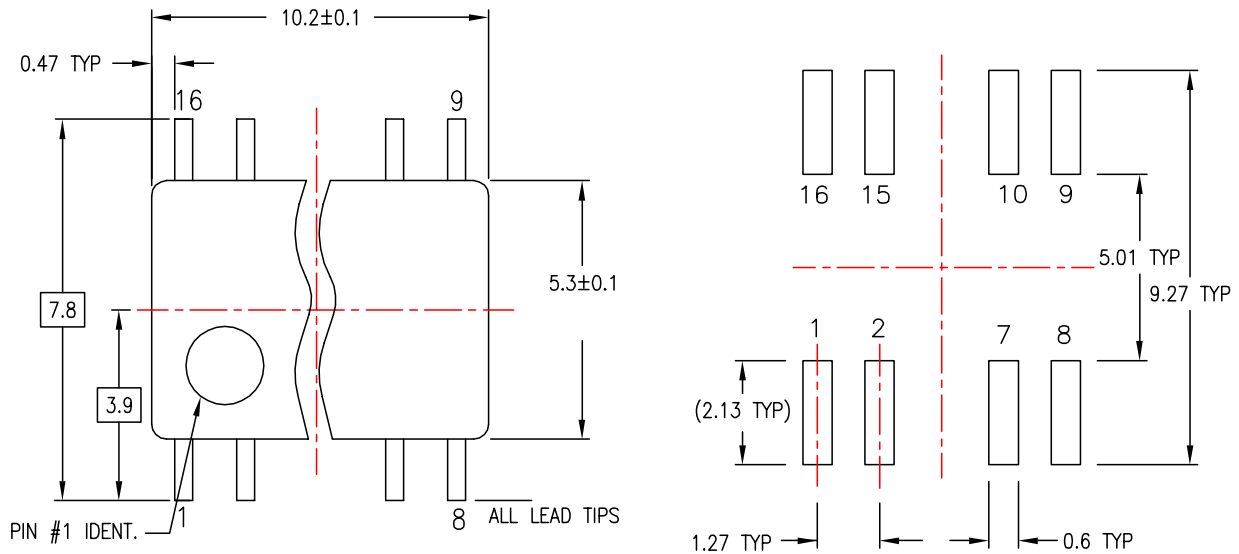
- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AC, ISSUE C, DATED MAY 1990.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) STANDARD LEAD FINISH:  
200 MICRONS / 5.08 MICRONS MIN.  
LEAD/TIN (SOLDER) ON COPPER.

M16AREVK

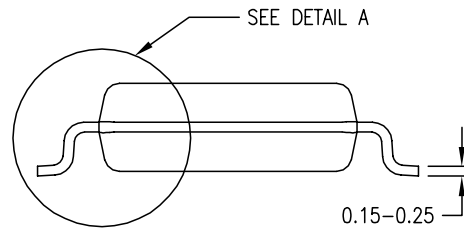
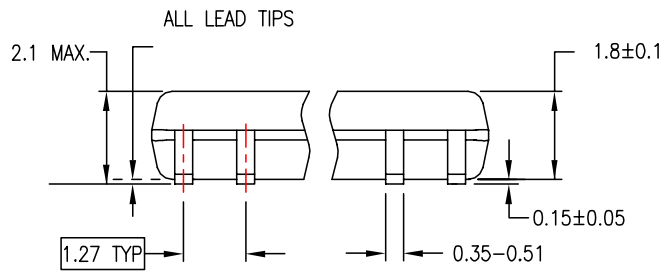
Figure 1. 16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M16A

**Physical Dimensions** (Continued)

Dimensions are in millimeters unless otherwise noted.



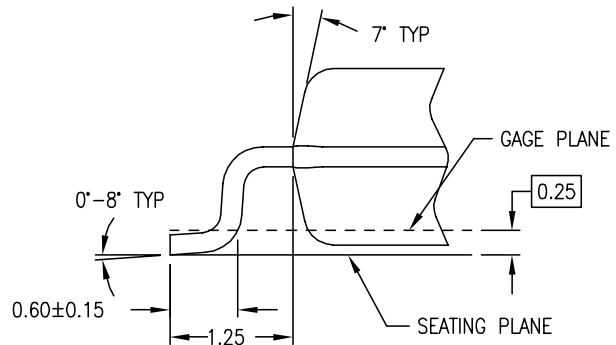
LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



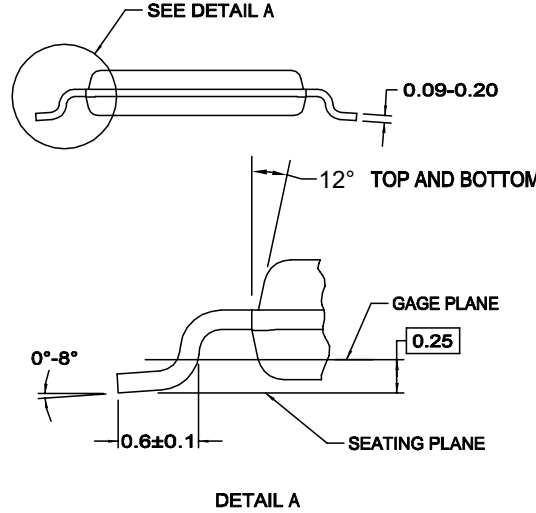
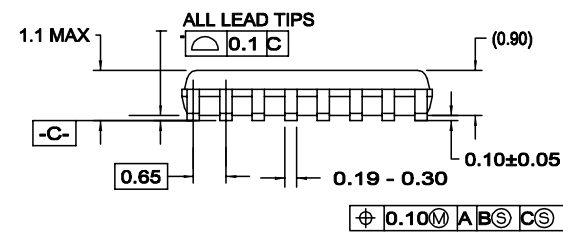
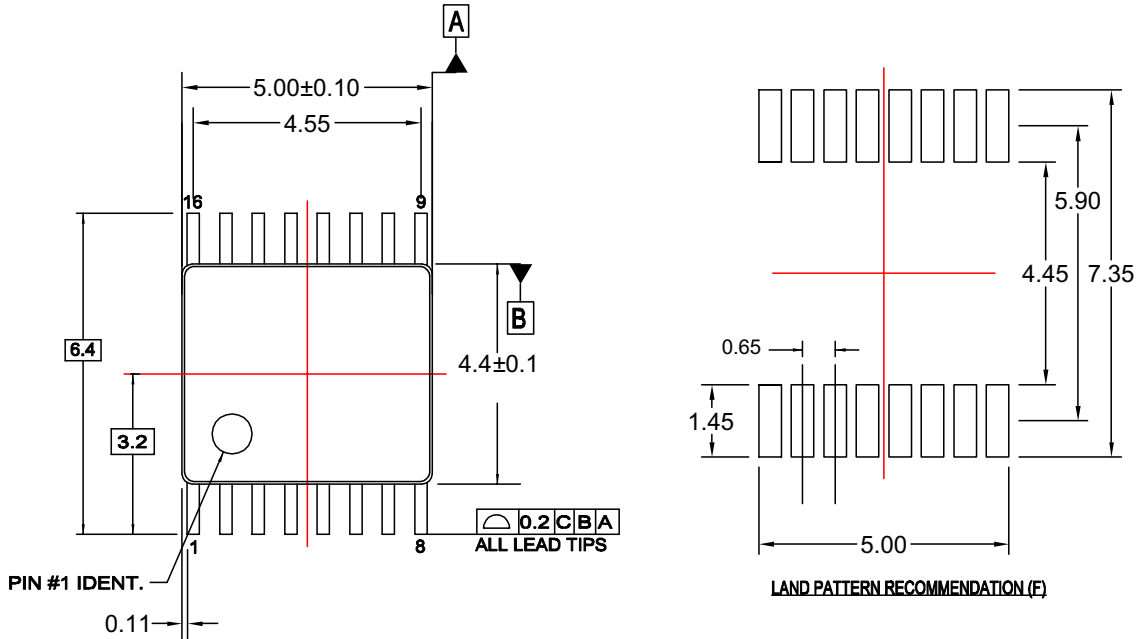
DETAIL A

M16DREVC

**Figure 2. 16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
Package Number M16D**

**Physical Dimensions** (Continued)

Dimensions are in millimeters unless otherwise noted.



- NOTES:**
- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB,
  - B. DIMENSIONS ARE IN MILLIMETERS
  - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
  - D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1994
  - E. DRAWING FILE NAME: MTC16REV4
  - F. LAND PATTERN RECOMMENDATION PER IPC7351 - ID# TSOP65P640X110-16N


MTC16rev4

**Figure 3. 16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC16**



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Across the board. Around the world. <sup>TM</sup>	ImpliedDisconnect <sup>TM</sup>	PowerTrench <sup>®</sup>	TinyBuck <sup>TM</sup>
ActiveArray <sup>TM</sup>	IntelliMAX <sup>TM</sup>	Programmable Active Droop <sup>TM</sup>	TinyLogic <sup>®</sup>
Bottomless <sup>TM</sup>	ISOPLANAR <sup>TM</sup>	QFET <sup>®</sup>	TINYOPTO <sup>TM</sup>
Build it Now <sup>TM</sup>	MICROCOUPLER <sup>TM</sup>	QS <sup>TM</sup>	TinyPower <sup>TM</sup>
CoolFET <sup>TM</sup>	MicroPak <sup>TM</sup>	QT Optoelectronics <sup>TM</sup>	TinyWire <sup>TM</sup>
CROSSVOLT <sup>TM</sup>	MICROWIRE <sup>TM</sup>	Quiet Series <sup>TM</sup>	TruTranslation <sup>TM</sup>
CTL <sup>TM</sup>	Motion-SPM <sup>TM</sup>	RapidConfigure <sup>TM</sup>	μSerDes <sup>TM</sup>
Current Transfer Logic <sup>TM</sup>	MSX <sup>TM</sup>	RapidConnect <sup>TM</sup>	UHC <sup>®</sup>
DOME <sup>TM</sup>	MSXPro <sup>TM</sup>	ScalarPump <sup>TM</sup>	UniFET <sup>TM</sup>
E <sup>2</sup> CMOS <sup>TM</sup>	OCX <sup>TM</sup>	SMART START <sup>TM</sup>	VCX <sup>TM</sup>
EcoSPARK <sup>®</sup>	OCXPro <sup>TM</sup>	SPM <sup>®</sup>	Wire <sup>TM</sup>
EnSigna <sup>TM</sup>	OPTOLOGIC <sup>®</sup>	STEALTH <sup>TM</sup>	
FACT Quiet Series <sup>TM</sup>	OPTOPLANAR <sup>®</sup>	SuperFET <sup>TM</sup>	
FACT <sup>®</sup>	PACMAN <sup>TM</sup>	SuperSOT <sup>TM</sup> -3	
FAST <sup>®</sup>	PDP-SPM <sup>TM</sup>	SuperSOT <sup>TM</sup> -6	
FASTr <sup>TM</sup>	POP <sup>TM</sup>	SuperSOT <sup>TM</sup> -8	
FPS <sup>TM</sup>	Power220 <sup>®</sup>	SyncFET <sup>TM</sup>	
FRFET <sup>®</sup>	Power247 <sup>®</sup>	TCM <sup>TM</sup>	
GlobalOptoisolator <sup>TM</sup>	PowerEdge <sup>TM</sup>	The Power Franchise <sup>®</sup>	
GTO <sup>TM</sup>	PowerSaver <sup>TM</sup>		
HiSeC <sup>TM</sup>			

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## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
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